

an outer array of contact pads, each of said contact pads separated from each other by a first distance;

a center array of contact pads, each of said contact pads separated by a second distance, said center array of contact pads being separated from said outer array of contact pads by a third distance which is larger than said first and second distances;

a plurality of solder balls attached to said contact pads of said substrate.

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46. (New) The ball grid array package of claim 29 wherein said outer array of contact pads is located outside an outer dimensional profile of an integrated circuit coupled to the top surface of said substrate.

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47. (New) The ball grid array package of claim 29 wherein said center array of contact pads is located inside the outer dimensional profile of an integrated circuit coupled to the top surface of said substrate.

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48. (New) The ball grid array package of claim 29 wherein said outer array of contact pads is located outside an outer dimensional profile of an integrated circuit coupled to the top surface of said substrate, and wherein said center array of contact pads is located inside the outer dimensional profile of said integrated circuit.

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49. (New) The ball grid array package of claim 29 wherein a distance between adjacent contact pads in said outer array is the same as the distance between adjacent contact pads in said center array.

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50. (New) The ball grid array package of claim 29 wherein the smallest distance between adjacent contact pads in the outer array is smaller than the

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distance between the outer array of contact pads and the center array of contact pads.

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51. (New) The ball grid array package of claim 29 wherein the top surface of said substrate has a ground bus that is connected to said center array of contact pads by a plurality of vias that extend through said substrate.

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Respectfully submitted,

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